



Technical Data Sheet EW 2050

			EW2050
Features			80 deg C trigger cure epoxy
Color			white
Viscosity[Pa·s] ^{*1}			70
Specific Gravity			1.3
Overlap Shear Strength [MPa] ^{*2}			
	Aluminum 2024		18
	Cold Rolled Steel		
	Stainless Steel 304		
		25°C	12
	Aluminum 2024	80°C	11
		120°C	13
		150°C	2
T-Peel Strength [kN/m] ^{*2}			
	Aluminum 1050		1
	Cold Rolled Steel		
Pressure Cooker Test[MPa] ^{*3}			
	Cold Rolled Steel	Initial	20
		Aging	25
Volume Resistivity [$\Omega \cdot \text{cm}$] ^{*4}			1×10^{16}
Surface Resistivity [Ω] ^{*4}			$>1.5 \times 10^{17}$
Dielectric Breakdown Voltage			20
		[kV/mm] * 4	
Dielectric Constant(f=1kHz) ^{*4}			3.6
Dissipation Factor(f=1kHz) ^{*4}			0.005
Thermal Coefficient of Expansion			7.0×10^{-5} (30-80 °C)
		[1/°C](0~80°C)	
Young Modulus [GPa]			
Glass Transition Temperature[°C]			109
Optimum Cure [min] ^{*5}			80 deg C- 60 min
		120°C	
		140°C	



PROS TECHNOLOGY

- *1 B type viscositymeter (BS, Spindle #7, 10rpm @25°C)
- *2 Size of Specimen:1.6×25×100mm(Shear)、0.8×25×150mm(Peel)
Area of Overlap:12.5×25mm(Shear),25×100mm(Peel)
Thickness of the bond line:0.1mm
Cure Condition:120°C×60min
Tensile Speed:5mm/min(Shear)、50mm/min(Peel)
Surface Preparation: Aluminum : FPL etch
Other substracts : Solvent wipe
- *3 Aging condition:134°C vapor @3atm ×24H
- *4 Tests per JIS K 6911
This is the time when the temperature of adhesive becomes the optimum cure temperature.
- *5